## NCE P-Channel Enhancement Mode Power MOSFET

### **Description**

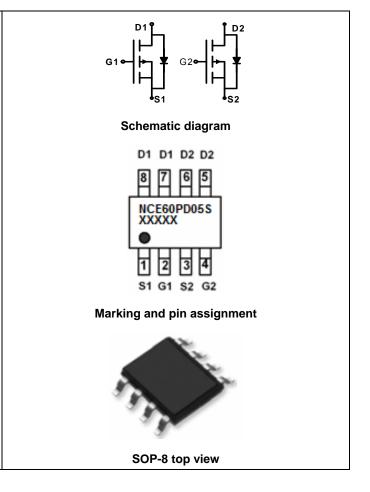
The NCE60PD05S uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

#### **General Features**

- $V_{DS}$  =-60V, $I_D$  =-5A  $R_{DS(ON)}$  <50m $\Omega$  @  $V_{GS}$ =-10V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

#### **Application**

- Power switching application
- Hard switched and high frequency circuits
- DC-DC Converter



#### **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE60PD05S	NCE60PD05S	SOP-8	Ø330mm	12mm	4000 units

### Absolute Maximum Ratings (T<sub>A</sub>=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	-60	V
Gate-Source Voltage	V <sub>G</sub> s	±20	V
Drain Current-Continuous	I <sub>D</sub>	-5	А
Drain Current-Continuous(T <sub>C</sub> =100 °C)	I <sub>D</sub> (100℃)	-3.5	Α
Pulsed Drain Current	I <sub>DM</sub>	-30	Α
Maximum Power Dissipation	P <sub>D</sub>	3	W
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 150	$^{\circ}$ C

#### **Thermal Characteristic**

Thermal Resistance ,Junction-to-Ambient <sup>(Note 2)</sup>	R <sub>θJA</sub>	42	°C/W
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# Electrical Characteristics (T<sub>A</sub>=25 $^{\circ}$ C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-60	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-60V,V <sub>GS</sub> =0V	-	-	-1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =-250μA	-1.5	-2.6	-3.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	$V_{GS}$ =-10 $V$ , $I_D$ =-5 $A$	-	40	50	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =-5V,I <sub>D</sub> =-5A	-	16	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C <sub>lss</sub>	\/ - 20\/\/ -0\/	-	2578	-	PF
Output Capacitance	Coss	$V_{DS}$ =-30V, $V_{GS}$ =0V, F=1.0MHz	-	112	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.UIVIFIZ	-	102	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>		-	10	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =-30 $V$ , , $R_L$ =30 $\Omega$	-	6	-	nS
Turn-Off Delay Time	$t_{d(off)}$	$V_{GS}$ =-10 $V$ , $R_{GEN}$ =3 $\Omega$	-	44	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	13	-	nS
Total Gate Charge	$Q_g$	V - 20VI - FA	-	46.2	-	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =-30V, $I_{D}$ =-5A, $V_{GS}$ =-10V	-	8.6	-	nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =-1UV	-	10.4	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	$V_{SD}$	V <sub>GS</sub> =0V,I <sub>S</sub> =-5A	-	-	-1.2	V
Diode Forward Current (Note 2)	Is		-	-	-5	Α

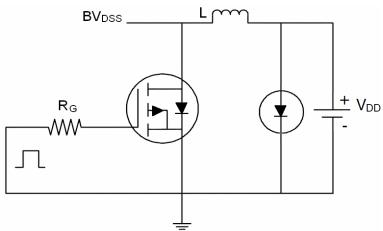
#### Notes:

- $\textbf{1.} \ \textbf{Repetitive Rating: Pulse width limited by maximum junction temperature}.$
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- 3. Pulse Test: Pulse Width  $\leq$  300 $\mu$ s, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production

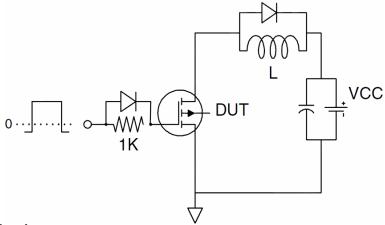


## **Test Circuit**

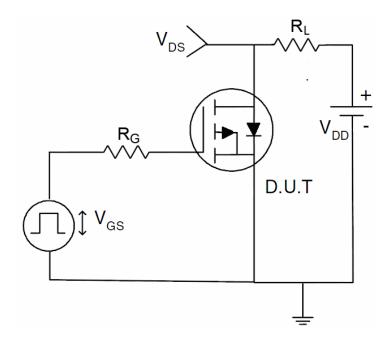
# 1) E<sub>AS</sub> Test Circuit



# 2) Gate Charge Test Circuit

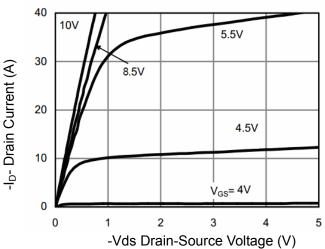


# 3) Switch Time Test Circuit

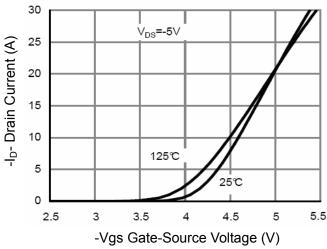




## **Typical Electrical and Thermal Characteristics**



**Figure 1 Output Characteristics** 



**Figure 2 Transfer Characteristics** 

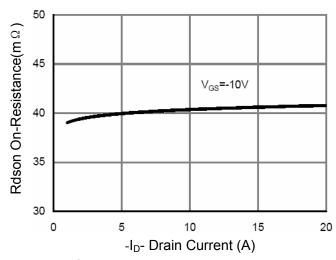
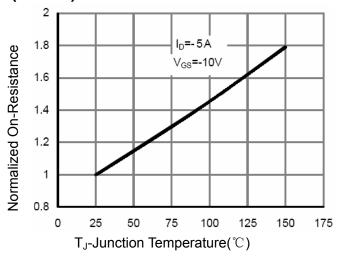


Figure 3 Rdson- Drain Current

#### (Curves)



**Figure 4 Rdson-Junction Temperature** 

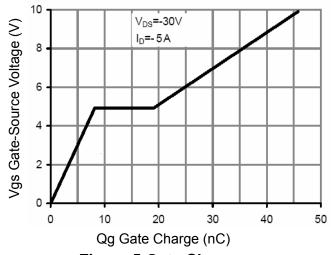


Figure 5 Gate Charge

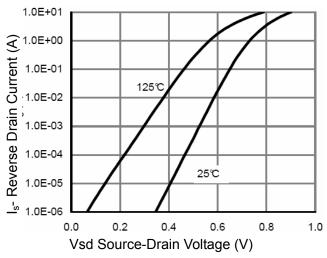


Figure 6 Source- Drain Diode Forward



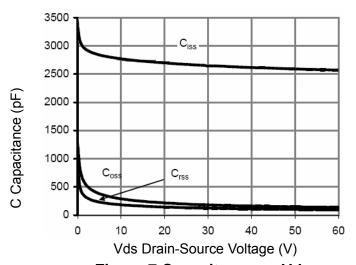


Figure 7 Capacitance vs Vds

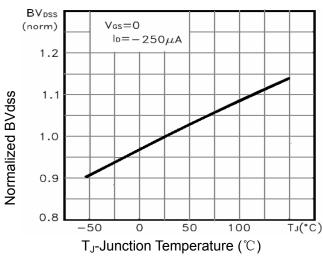
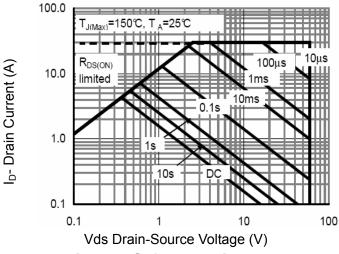


Figure 9 BV<sub>DSS</sub> vs Junction Temperature



**Figure 8 Safe Operation Area** 

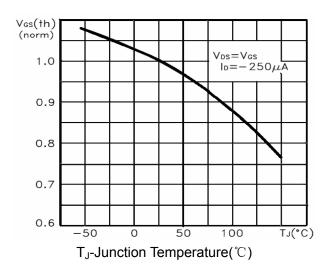


Figure 10 V<sub>GS(th)</sub> vs Junction Temperature

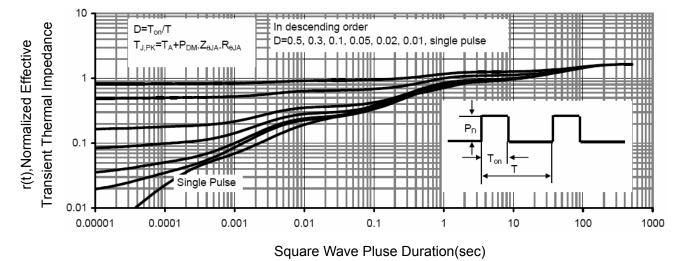
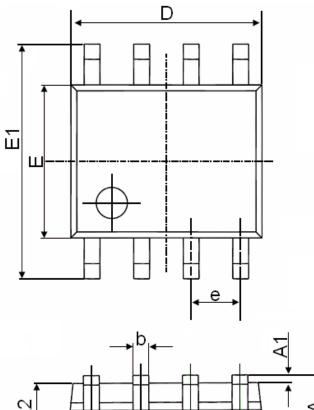
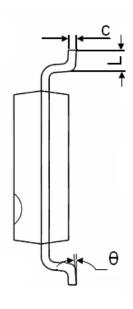


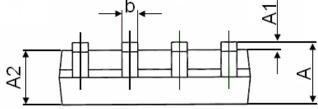
Figure 11 Normalized Maximum Transient Thermal Impedance



# **SOP-8 Package Information**







Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
Е	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270	1.270(BSC)		(BSC)	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	



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